	CONNECTING CS INDUSTRIES® INTERNATIONAL AND PARTICIPAL COMPONENTIES	Osition Dec PC, Bannockb -American co	c laration ourn, Illinois. A opyright conve	Il rights reserved untions.	under both	This docume level parts, t	ent is a declaration	tion of t encomp	he substances basses all low	s within the ser level mate	manufacture erials for wh	er listed it hich the m	em. Note: i anufacture	if the item is an as r has engineering	sembly with loweresponsibility.
1752-21.1					Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ous Materia	als and Mfg Information			
Supplier	r Information														
Company name* Con				Company unique ID			Unique ID Authority					Response Date*			
onsemi												2023-06-08			
Contact N	lame	Title - Contact]	Phone - Contact*				Email - Contact*					
Product-I	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
uthorize	ed Representative*	Title - Representative]	Phone - Representative*				Email - Representative*					
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Date	Effective DateVersionManufacturing Sit2023-06-08PHM		ng Site	1	Weight*	UOM	Unit Type	
		L78M05T-TL-E Line		Linear regulator	inear regulator					РНМ		3	800.0	mg	Each
/anufa	cturing Proccess Informat	ion													
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-020		J-STD-020 MS	L Rating	Peak Process Body Temperat		ure Max Time at Peak Tempe		Temperat	ure Num	ber of Reflow Cyc	les	
contains Bi		CU Alloy NA			0 C		30 se		secon	ds 3					
omments	3														
or more	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.21	mg	Supplier	Silicon (Si)	7440-21-3		3.1981	mg
			Supplier	Polyimide	Proprietary Data		0.0119	mg
Die Attach	0.94	mg	Supplier	Silver (Ag)	7440-22-4		0.0282	mg
			А	Lead (Pb)	7439-92-1	7a	0.8836	mg
			Supplier	Tin (Sn)	7440-31-5		0.0188	mg
			Supplier	Copper (Cu)	7440-50-8		0.0094	mg
ead Frame	154.1	mg	Supplier	Tin (Sn)	7440-31-5		0.2157	mg
			Supplier	Copper (Cu)	7440-50-8		153.8843	mg
Iold Compound-Black	138.27	mg		Brominated epoxy resin	proprietary data		1.7975	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		15.9011	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		2.7654	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6913	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		14.7949	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		102.3198	mg
Plating	3.4	mg	В	Bismuth (Bi)	7440-69-9		0.0204	mg
			Supplier	Tin (Sn)	7440-31-5		3.3796	mg
Wire Bond - Au	0.08	mg	Supplier	Gold (Au)	7440-57-5		0.08	mg